

Features

Industrial Carrier Design

- Micro-ATX form factor: 9.6 x 9.6 inches (244 x 244mm)
- Made in the USA
- -40°C to +85°C with supporting cooling options
- ATX Mode: Standard ATX Power input
- AT Mode: 12VDC +/- 5%
- Supports all interfaces on the WINSYSTEMS COMeT6 Modules

Graphics

- 3x DisplayPort++ Ports
- Support for Dual Channel LVDS and eDP, including backlight

USB I/O

- 4x USB 3.2 Gen1 (2x Front Panel Type A, 2x Header)
- 4x USB 2.0 (2x Front Panel, 2x Header)

Serial UART I/O

- 2x RS 232 2pin (Tx/Rx) from COMe Module
- 2x RS232/422/485 Multiprotocol Legacy mode

Storage/SATA Channels

- 4x SATA Type III (6Gb/s) channels

Network

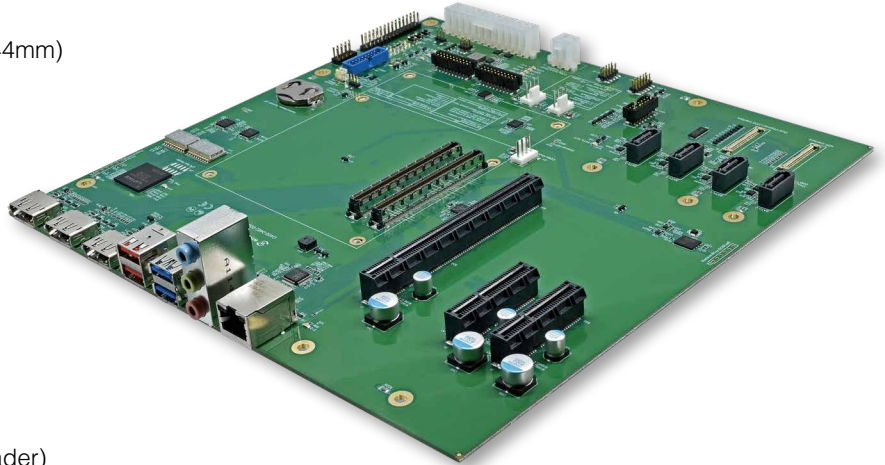
- 1x RJ45 supporting 2.5G Ethernet from COMe

PCI Express Expansion

- 1x PCI Express Gen4 x16 PEG / NVMe
- 2x PCI Express Gen3 x4

Software

- Windows 10 and 11
- Linux



Product Description

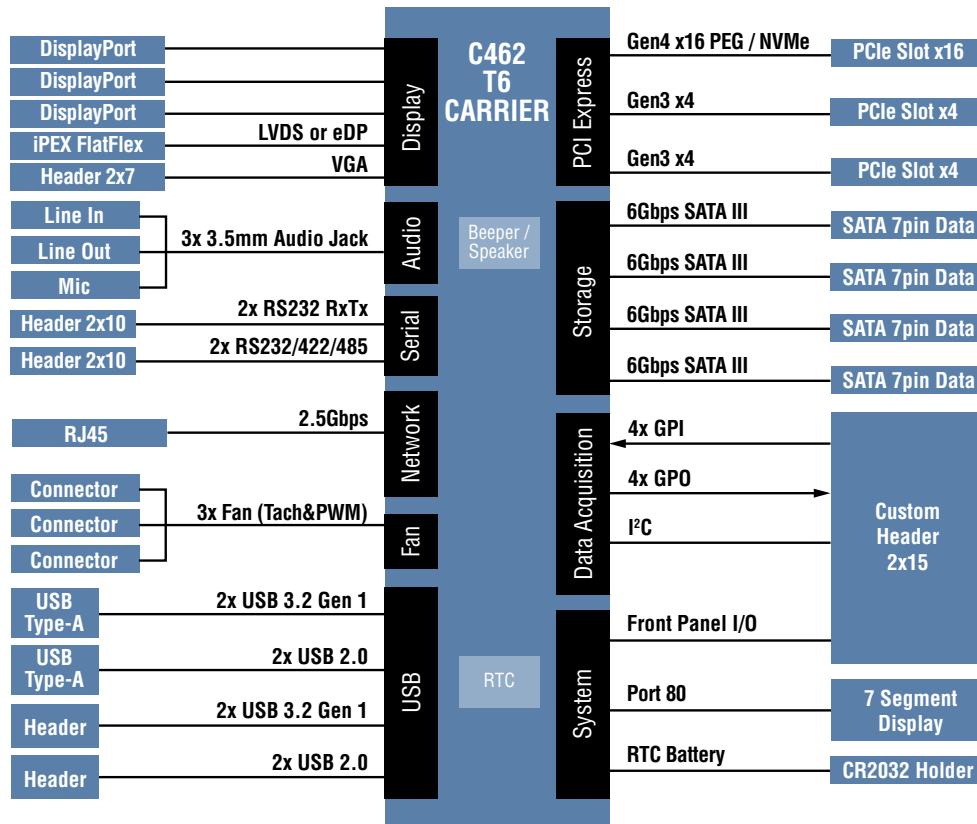
The ATX-M-CC462-T6 is a fully featured COM Express Type 6 carrier board designed to use industry standard COM Express Type 6 modules including the WINSYSTEMS COMeT6-TGLU Series of COM Express Type 6 modules featuring the Intel® Tiger Lake UP3 SOC.

The carrier implements the full capabilities of the Type 6 connectors and is compliant with PICMG® COM Express Rev 3.0 Specifications. The ATX-M-CC462-T6 carrier board has multiple interface options including 3x PCIe slots, multiple Video options, 4x SATA devices, 8x USB ports (2.0 and 3.1), and high speed 2.5Gbps Ethernet that make it highly configurable for use in any application.

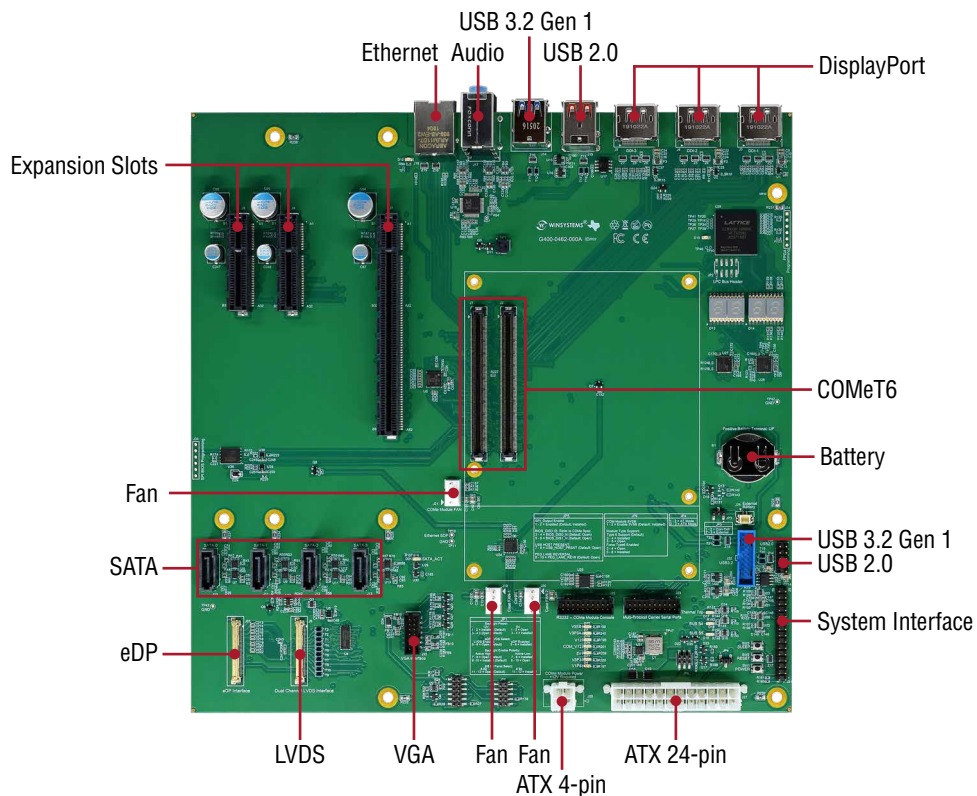
This is a production-ready reference board which can be taken directly into production for customer use, or available schematics and layout can be leveraged for customers working to design their own carrier.

The carrier board is designed to support a wide range of commercial, industrial, and automotive applications across a wide temperature spectrum (-40°C to +85°C).

Block Diagram



Connectors



Technical Specifications

FORM FACTOR	<ul style="list-style-type: none"> Micro-ATX 9.6 x 9.6 inches (244 x 244mm)
STORAGE	<ul style="list-style-type: none"> 4x SATA Type III (6Gb/s) channels
DISPLAY	<ul style="list-style-type: none"> Quad Simultaneous Displays 3x DisplayPort++ Support for Dual Channel LVDS and eDP including backlight VGA
NETWORK INTERFACE	<ul style="list-style-type: none"> 1x 2.5G Ethernet
ONBOARD I/O	<ul style="list-style-type: none"> 4x USB 3.2 Gen1 (2x Front Panel Type A, 2x Header) 4x USB 2.0 (2x Front Panel Type A, 2x Header) 2x RS 232 2pin (Tx/Rx) from COMe Module 2x RS232/422/485 Multiprotocol Legacy mode 1x PCIe Gen4 x16 slot 2x PCIe Gen3 x4 slot 1x EEPROM socket 1x LPC header 3x Fan Header 1x GPIO/Feature connector
FRONT PANEL CONNECTORS	<ul style="list-style-type: none"> 1x 2.5 Ethernet RJ45 port 1x Audio with separate 3.5mm jacks for MIC, LINE-OUT, LINE-IN 3x Standard DisplayPort connectors 2x USB 3.1 Type A connector 2x USB 2.0 Type A connector
POWER	<ul style="list-style-type: none"> ATX Mode: Standard ATX Power input AT Mode: 12VDC +/- 5%
ENVIRONMENTAL	<ul style="list-style-type: none"> Operating Temperature -40°C to +85°C with supporting cooling options Storage Temperature -40°C to +85°C Thermal Shock Operational Temperature limit exposures in <1 minute Shock IAW IEC60068-2-27 Half Sine Wave, 50g/11ms Vibration IAW IEC60068-2-27 Random waveform, 10Hz-2KHz, 7g CE Compliant CISPR B and FCC Class B ESD (Human body) – JEDEC Standard JA114/JS-001
MECHANICAL	<p>Dimensions: 6.7 in x 6.7 in (mITX) (170 mm x 170 mm)</p> <p>Weight: 8.0 oz (225 gm) without COMe Module</p> <p>PC Board thickness: 0.078 inches (2.0 mm)</p>
SOFTWARE	<ul style="list-style-type: none"> Windows 10 and 11 Linux

Order Information

SBC PART NUMBER	ATX-M-CC462-T6 m = Module installed (0 = no module is default) t = Thermal solution installed (0 = no thermal solution is default)	
COM EXPRESS TYPE 6 REFERENCE MODULES	ATX-M-CC462-T6	COM Express Type 6 Compact Module
CABLES AND ACCESSORIES	CBL-PWR-125-20	Input Power Cable

Expansion and Customization Options

WINSYSTEMS provides customization options for OEMs with minimum order quantities. Please contact an Application Engineer for details. Additional cables, expansion cards, power supplies, and solid-state drives to complete your embedded computing solution including data acquisition, communications, location, and other features are available. Our Application Engineers are available to guide you through product selection and customized options.

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Contact us for more information about this new product.



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